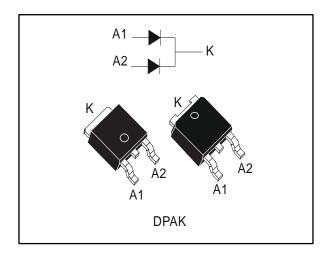
# STPS640C



## Power Schottky rectifier

Datasheet - production data



### **Features**

- Very small conduction losses
- Extremely fast switching
- Low thermal resistance
- Negligible switching losses
- Low forward voltage drop
- Low capacitance
- Avalanche specification
- ECOPACK<sup>®</sup>2 compliant component for DPAK on demand

### **Description**

This dual Schottky rectifier is designed for switch mode power supplies and other power converters.

This device is intended for use in low and medium voltage operation, and in particular high frequency circuits where low switching losses are required (free wheeling and polarity protection).

**Table 1: Device summary** 

Symbol	Value
I <sub>F(AV)</sub>	2 x 3 A
$V_{RRM}$	40 V
T <sub>j</sub> (max)	150 °C
V <sub>F</sub> (typ)	0.50 V

Characteristics STPS640C

### 1 Characteristics

Table 2: Absolute ratings (limiting values at 25 °C, per diode, unless otherwise specified)

Symbol	Parameter	Value	Uni t	
$V_{RRM}$	Repetitive peak reverse voltage		40	V
I <sub>F(RMS)</sub>	Forward rms current	6	Α	
I <sub>F(AV)</sub>	Average forward current $\delta$ = 0.5, square wave	3	Α	
I <sub>FSM</sub>	Surge non repetitive forward current	75	Α	
P <sub>ARM</sub>	Repetitive peak avalanche power		90	W
T <sub>stg</sub>	Storage temperature range	-65 to +150	°C	
Tj	Maximum operating junction temperature (1)	150	°C	

#### Notes:

**Table 3: Thermal parameters** 

Symbol	Parameter Ma			Unit
В	Junction to case	Per diode	5.5	
R <sub>th(j-c)</sub>	Junction to case	Per device	3	°C/W
R <sub>th(c)</sub>	Coupling		0.5	

When the diodes 1 and 2 are used simultaneously:

 $\Delta T_{j \text{ (diode1)}} = P_{\text{(diode1)}} x R_{\text{th(j-c)}} \text{ (per diode)} + P_{\text{(diode2)}} x R_{\text{th(c)}}$ 

Table 4: Static electrical characteristics (per diode)

Symbol	Parameter	Test conditions		Min.	Тур.	Max.	Unit
I <sub>R</sub> <sup>(1)</sup>	(1) Reverse leakage current	T <sub>j</sub> = 25 °C	V <sub>R</sub> = V <sub>RRM</sub>	-		100	μΑ
IR <sup>(*)</sup>		T <sub>j</sub> = 125 °C		-	2	10	mA
		T <sub>j</sub> = 25 °C	I <sub>F</sub> = 3 A	-		0.63	V
V <sub>F</sub> <sup>(2)</sup>		T <sub>j</sub> = 125 °C		-	0.50	0.57	
VF(=)	Forward voltage drop	T <sub>j</sub> = 25 °C	I <sub>F</sub> = 6 A	-		0.84	
		T <sub>j</sub> = 125 °C		-	0.67	0.72	

#### Notes:

 $^{(1)}$ Pulse test:  $t_p$  = 5 ms,  $\delta$  < 2%

 $^{(2)}$ Pulse test:  $t_p$  = 380  $\mu$ s,  $\delta$  < 2%

To evaluate the conduction losses, use the following equation:

 $P = 0.42 \text{ x } I_{F(AV)} + 0.050 \text{ x } I_{F^2(RMS)}$ 

 $<sup>^{(1)}(</sup>dP_{tot}/dT_j) < (1/R_{th(j-a)}) \ condition \ to \ avoid \ thermal \ runaway \ for \ a \ diode \ on \ its \ own \ heatsink.$ 

STPS640C Characteristics

### 1.1 Characteristics (curves)

Figure 1: Average forward power dissipation

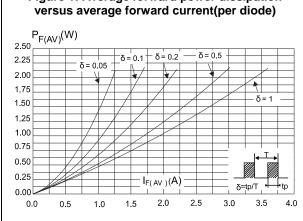


Figure 2: Average forward current versus ambient temperature (per diode,  $\delta$  = 0.5)  $I_{F_{(AV)}}(A)$ 

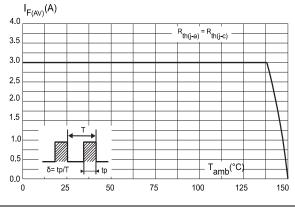


Figure 3: Normalized avalanche power derating versus pulse duration (T<sub>j</sub> = 125 °C)

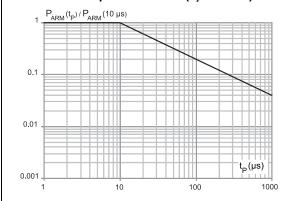


Figure 4: Relative variation of thermal impedance junction to case versus pulse duration

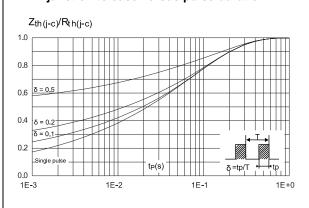


Figure 5: Reverse leakage current versus reverse voltage applied (typical values, per diode)

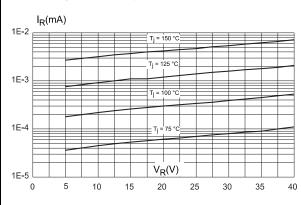
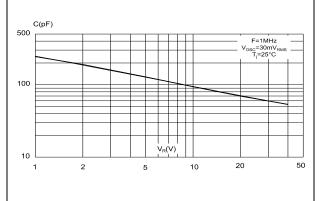


Figure 6: Junction capacitance versus reverse voltage applied (typical values, per diode)



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Figure 7: Forward voltage drop versus forward current (maximum values, per diode)

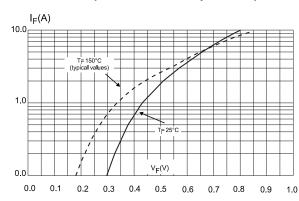
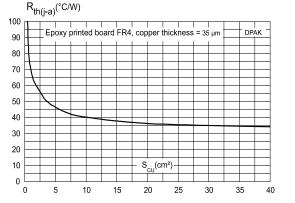


Figure 8: Thermal resistance junction to ambient versus copper surface under tab



STPS640C Package information

## 2 Package information

In order to meet environmental requirements, ST offers these devices in different grades of ECOPACK® packages, depending on their level of environmental compliance. ECOPACK® specifications, grade definitions and product status are available at: **www.st.com**. ECOPACK® is an ST trademark.

- Cooling method: by conduction (C)
- Epoxy meets UL 94,V0

## 2.1 DPAK package information

Figure 9: DPAK package outline **b4** c2, Thermal pad **E1** L2 D1 D R Gauge 0.25 plane



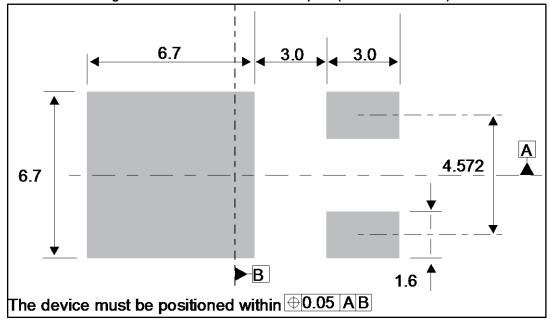
This package drawing may slightly differ from the physical package. However, all the specified dimensions are guaranteed.

Package information STPS640C

Table 5: DPAK package mechanical data

	Dimensions				
Ref.	Ref. Millin		Incl	nches	
	Min.	Max.	Min.	Max.	
А	2.18	2.40	0.085	0.094	
A1	0.90	1.10	0.035	0.043	
A2	0.03	0.23	0.001	0.009	
b	0.64	0.90	0.025	0.035	
b4	4.95	5.46	0.194	0.215	
С	0.46	0.61	0.018	0.024	
c2	0.46	0.60	0.018	0.023	
D	5.97	6.22	0.235	0.244	
D1	4.95	5.60	0.194	0.220	
Е	6.35	6.73	0.250	0.265	
E1	4.32	5.50	0.170	0.216	
е	e 2.28		. 0.090 typ.		
e1	4.40	4.70	0.173	0.185	
Н	9.35	10.40	0.368	0.409	
L	1.0	1.78	0.039	0.070	
L2		1.27		0.050	
L4	0.60	1.02	0.023	0.040	
V2	-8°	+8°	-8°	+8°	

Figure 10: DPAK recommended footprint (dimensions in mm)



STPS640C Ordering information

# 3 Ordering information

**Table 6: Ordering information** 

Order code Marking		Marking	Package	Weight	Base gty	Delivery mode
	Order Code	wai Kiliy	rackage	weight	Dase quy	Delivery Illoue
	STPS640CB	S6 40C	DDAK	0.00 =	75	Tube
	STPS640CB-TR	S6 40C	DPAK	0.32 g	2500	Tape and reel

# 4 Revision history

**Table 7: Document revision history** 

Date	Revision	Changes
Aug-2003	6B	Last issue
22-Mar-2007	7	Updated Figure 8 Updated ECOPACK statement.
20-Nov-2014	8	Figure 3. Removed PARM (Tj = 25 °C), TO-220AB and TO-220FPAB package information.
16-May-2017	9	Updated DPAK package information and reformatted to current standard.

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